WEE, wafer edge expose LHP, lo temp hot plate CPL, chill plate CHP, chilling hot plate ADH, HMDS dispense and hot plate UNC, unicassette station PRA, the main robot IRA, interface robot CRA, Cassette stage robot CWH, cup wash DEV, developer COT, coater TCT, top coater SBU, stationary buffer EIS, wafer handoff to the stepper TCP, transition chill plate TRS, transition station PUP, engineering cassette station

	2-1 COT		2-2 TCT		1-5 PUP	
u		1.5	-	une:		
1			2-4 DEV			UNC
3-4 WEE 3-5 EIS 3-0 IRA	2-15 CPL			2-5 ADH	1-0 CRA	1-1
	2-16 TRS			2-6		1-2 UNC
	2-17 CPL			2-7 TCP-R		
	2-18			2-8 TRS-R		
	2-19 CPL			2-9 CPL		
	2-20			2-10 CWH		
	2-21 CHP	2-26 LHP		2-11 CPL		1-3 UNC
	2-22 CHP	2-29 HHP 2-28 LHP 2-27 LHP		2-12 LHP		
	2-23 CHP			2-13 LHP		1-4 UNC
	2-24 LHP			2-14 HHP		
	3-0 IRA U	2-23 CHP 2-22 CHP 2-22 CHP 2-21 CHP 2-21 CHP 2-20 2-19 CPL 2-18 2-19 CPL 2-18 2-17 CPL 2-15 CPL 0 U	2-23 CHP 2-28 C 2-23 CHP 2-28 C 2-22 CHP 2-27 C 2-21 CHP 2-26 C 2-21 CHP 2-26 C 2-20 2-26 C 2-19 CPL 2-26 C 2-27 CPL 2-26 C 2-28 CHP 2-28 C 2-28 CHP 2-28 C 2-28 CHP 2-28 C 2-27 CHP 2-27 C 2-28 CHP 2-28 C 2-27 CHP 2-27 C 2-28 CHP 2-27 C 2-27 CHP 2-26 C 2-26 CHP 2-26 C 2-27 CHP 2-26 C 2-29 CHP 2-26 C 2-19 CPL 2-26 C 2-19 CPL 2-26 C 2-19 CPL 2-26 C 2-18 2-0 C 2-16 CPL 2-0 C 2-18 2-0 C 2-15 CPL 2-0 C 2-1	2-23 CHP 2-28 LHP 2-22 CHP 2-27 LHP 2-21 CHP 2-27 LHP 2-21 CHP 2-26 LHP 2-20 2-26 LHP 2-19 CPL 2-25 LHP 2-18 2-17 CPL 2-16 TRS 2-0 PRA 2-15 CPL 2-0 PRA 0 2-3 DEV 2-4 D	2-23 CHP 2-28 LHP 2-13 LHP 2-22 CHP 2-27 LHP 2-12 LHP 2-22 CHP 2-27 LHP 2-12 LHP 2-21 CHP 2-26 LHP 2-11 CPL 2-20 2-25 LHP 2-10 CMH 2-19 CPL 2-25 LHP 2-10 CMH 2-19 CPL 2-20 PRA 2-8 TRS-R 2-17 CPL 2-0 PRA 2-8 TRS-R 2-15 CPL 2-0 PRA 2-6 2-15 CPL 2-3 DEV 2-4 DEV	2-23 CHP 2-28 LHP 2-13 LHP 2-22 CHP 2-27 LHP 2-13 LHP 2-22 CHP 2-27 LHP 2-12 LHP 2-21 CHP 2-26 LHP 2-11 CPL 2-20 2-26 LHP 2-11 CPL 2-19 CPL 2-25 LHP 2-10 CWH 2-19 CPL 2-25 LHP 2-9 CPL 2-18 2-9 CPL 2-9 CPL 2-16 TRS 2-0 PRA 2-6 2-15 CPL 2-0 PRA 2-6 2-15 CPL 2-3 DEV 2-4 DEV

 $(0\% \times OD \times OH)$